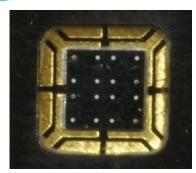
Surface Mount Quad Photodiode

Electronics

OPR5911

Features:

- Surface mountable
- Closely matched responsivity
- High temperature operation
- Common cathode connections



Description:

Each OPR5911 device is a four-element photodiode that is enclosed in a compact polyimide chip carrier and designed for a variety of encoder and control applications. The single chip construction ensures excellent matching and very tight dimensional tolerances between active areas. The custom opaque package shields the photodiodes from stray light and can withstand multiple exposures to the most demanding soldering conditions, while the wraparound gold-plated solder pads offer exceptions storage and wetting characteristics.

All cathodes in the OPR5911 are bonded together, which enables the elements to act in unison with limited external circuitry.

See Application Bulletin 237 for handling considerations.

Applications:

- Encoder applications
- Control applications

Ordering Information							
Part Number	Receiver Type	# of Elements	Responsivity (mA/mW) Min.	Reverse Voltage Min.	Active Area (mm²)	Packaging	
OPR5911	Photodiode Array	4	0.45	14	1.61 (each)	Chip Tray	

OPR5911

0.063

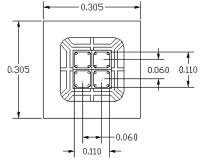


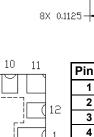


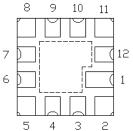
ESD (Human Body Model)











Pin#	Function	Pin#	Function	
1	Anode 1	7	Anode 3	
2	2 Common Cathode		Common Cathode	
3	N. C. / N.C.	9	N. C. / N.C.	
4	N. C. / N.C.	10	N. C. / N.C.	
5	Common Cathode	11	Common Cathode	
6	Anode 2	12	Anode 4	

8X 0.049

8X 0.059

General Note

SYMBOLIZATION AREA

UNLESS OTHERWISE

SPECIFIED, ALL TOLERANCES ARE

±.005"

Surface Mount Quad Photodiode



Electrical Specifications

Absolute Maximum Ratings (T_A = 25° C unless otherwise noted)

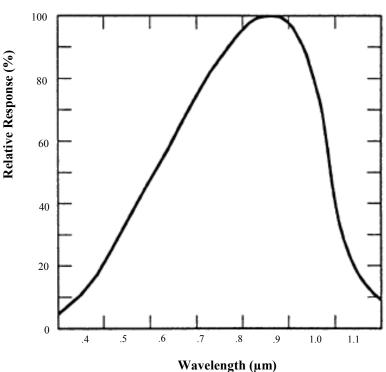
Storage and Operating Temperature	-55° C to +125° C
Reverse Breakdown Voltage	14 V / minute
Solder reflow time within 5°C of peak temperature is 20 to 40 seconds ⁽¹⁾	250° C

Electrical Characteristics (T_A = 25° C unless otherwise noted)

SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS	TEST CONDITIONS
R	Responsivity	0.45	ı	١	A/W	$E_e = 10 \mu W$, $\lambda = 850 \text{ nm}$, $V_R = 0$
V_{BR}	Reverse Breakdown Voltage	14	-	1	V	Ι _R = 100 μΑ
I _D	Reverse Dark Current	_	_	30	nA	V _R = 10 V
C _T	Capacitance	_	10	-	pF	V _R = 10 V
LXW	Active Area (per diode)	_	1.61		mm ²	(1.27 mm x 1.27 mm)

Notes:

Spectral Responsivity



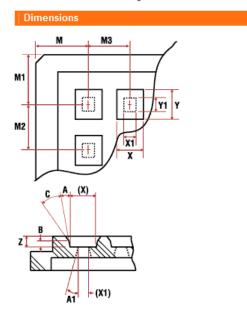
^{1.} Solder time less than 5 seconds at temperature extreme.

Surface Mount Quad Photodiode



Packaging

Bare Die/CSP Tray Detail



POCKET LOCATIONS

M = 0.592" ±0.005"

M1 = 0.592" ±0.005"

M2 = 0.401" ±0.005"

M3 = 0.401" ±0.005"

Array = 8x8 (64)

POCKET DETAILS

X = 0.361" ±0.005" pocket size
Y = 0.361" ±0.005" pocket size
Z = 0.100" ±0.005" pocket depth
A = 5° ±1/2° pocket draft angle
No Cross Slots

OVERALL TRAY SIZE

Size = 3.990" ±0.010" Height = 0.315" +0.005" -0.005" Flatness = 0.020"

H44-359-62C02



Orientation

